

L Number	Hits	Search Text	DB	Time stamp
1	64	73/204.26.ccls. and silicon and nitride	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:05
8	58	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:20
15	55	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane) and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:23
22	17	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 19:03
29	15	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6)) and (contact terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:42
36	14	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 sens\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 19:06
-	279	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:04
-	9	("5423212" "5393351" "5703287").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:06
-	200	73/204.26.ccls. and (membrane coat\$4 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
-	1	73/204.26.ccls. and (membrane coat\$4 layer) and impermeable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
-	2	("4682503" "4766666").PN.	USPAT	2002/01/24 17:20
-	27	4766666.URPN.	USPAT	2002/01/24 17:20